

A 12-GHz, 12-W HJFET Amplifier with 48% Peak Power-Added Efficiency

Kohji Matsunaga, Yasuhiro Okamoto, and Masaaki Kuzuhara, *Member, IEEE*

Abstract—This letter describes a Ku-band power amplifier fabricated with a one-chip $0.45\text{ }\mu\text{m} \times 16.8\text{ mm}$ GaAs-based heterojunction FET (HJFET), in which a 40.9 dBm (12.3 W) output power with 48% power-added efficiency (PAE) and 10.1 dB linear gain was achieved at 12 GHz. To our knowledge, this is the highest PAE, gain and output power combination achieved by a single FET power amplifier at this frequency.

I. INTRODUCTION

THERE is a growing demand for solid state power amplifiers (SSPA's) that are capable of delivering increased output power with reasonable efficiency. Power GaAs MESFET's with over 10 W output power have already been reported at Ku-band [1], [2]. However, because of the increased chip size and the limited gain performance of the GaAs MESFET's, further improvements in the output power from a single MESFET chip are becoming rather difficult.

Recently, a GaAs-based heterojunction FET (HJFET) has emerged as a viable candidate for microwave power applications. This device has demonstrated excellent performance of high output power, gain and PAE, making it attractive for various SSPA applications [3]–[11]. This is due to its inherent high drain current and high gain characteristics along with its high gate breakdown voltages [5], [7], [10]–[12]. To minimize power combining loss in the multiwatt power amplifiers, large-periphery devices capable of providing higher output power density with higher efficiency are of great interest.

To date, GaAs-based heterojunction FET's with small gate periphery have already demonstrated impressive power performance. These include an output power of 0.6 W, 75.8% PAE with 1.2-mm gate-width at 10 GHz [7] and 0.97 W, 70% PAE with 1.2-mm gate-width at 10 GHz [9]. More recently, impressive results have been reported on larger-periphery devices, in which an output power level of 6 W with PAE of greater than 50% has been achieved at 12 GHz [11], [13]. In order to further improve the output power level under high PAE, we have developed a larger gate-width HJFET with state-of-the-art output power and efficiency at Ku-band.

In this letter, a record power performance of an amplifier composed of a single HJFET chip with internal matching circuits is described.

II. HJFET AMPLIFIER

Step-recessed $0.45\text{-}\mu\text{m}$ gate-length HJFET's were fabricated on a 3-in. GaAs substrate. The layer structure is the same as that described in our previous report [13]. The active part of the MBE-grown HJFET structure consists of a 130\AA undoped $\text{In}_{0.2}\text{Ga}_{0.8}\text{As}$ channel layer sandwiched between two Si-doped $\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$ layers. The doping densities for the upper (80\AA) and the lower (40\AA) AlGaAs donor layers are 4.5×10^{18} and $4 \times 10^{18}\text{cm}^{-3}$, respectively. To achieve high gate-to-drain breakdown voltage BV_{gd} while maintaining high maximum drain current (I_{max}), an n^+/n dual cap layer and an undoped AlGaAs Schottky layer were employed [12]. After thinning the device thickness to $30\text{ }\mu\text{m}$, slot via-holes were etched underneath each source pad. The flip-side of the wafer was then plated with $20\text{ }\mu\text{m}$ of gold to reduce source inductance as well as to ensure low thermal resistance.

The device exhibited a drain saturation current of 270 mA/mm with I_{max} of 550 mA/mm . I_{max} was defined as a drain current measured at a gate bias of $+1\text{ V}$. The device exhibited a maximum transconductance of 370 mS/mm and a BV_{gd} of more than 12 V . Microwave S-parameter measurements, performed from 0.5 to 40 GHz for a $100\text{-}\mu\text{m}$ device, exhibited a peak power-gain cutoff frequency of 158 GHz . The power performance of a 1.05-mm gate-width HJFET evaluated at 12 GHz was 810-mW output power, 10-dB associated gain, and 60% PAE. The device was biased for Class AB operation at $V_d = 7\text{ V}$.

A one-chip device with a total gate-width of 16.8 mm was used as a power amplifier building block. The output matching circuit was designed using a large-signal load impedance determined from load-pull measurements performed on a 1.05-mm HJFET. The input and output matching circuits consist of L-C-L section transformers, quarter wave transformers and low-impedance transmission lines. The input matching circuit was designed to achieve higher gain by using the small-signal equivalent circuit of a 16.8-mm HJFET. The low-impedance transmission lines were used to reduce the insertion loss in the matching circuits.

Fig. 1 shows the photograph of the internally matched HJFET power amplifier fabricated. The L-C-L section transformer is composed of a metal-insulator-metal capacitor with $150\text{-}\mu\text{m}$ -thick barium titanate and bonding wire inductors. The quarter wave transformer and low-impedance transmission lines were formed on a $250\text{-}\mu\text{m}$ -thick alumina substrate. The package size of the power amplifier, excluding the bias lines, was $16.5 \times 9.7\text{ mm}^2$ with an actual circuit size of $5.0 \times 7.5\text{ mm}^2$.

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The authors are with Kansai Electronics Research Laboratories, NEC Corporation, Shiga 520, Japan.
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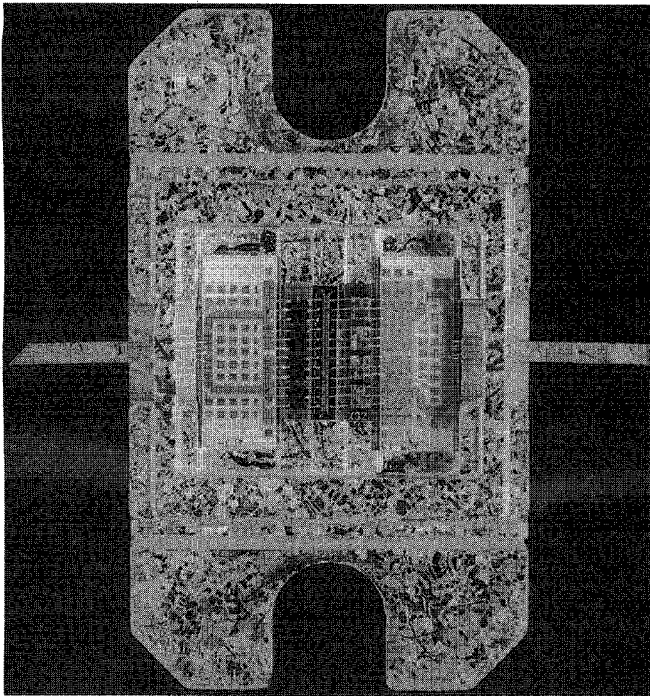
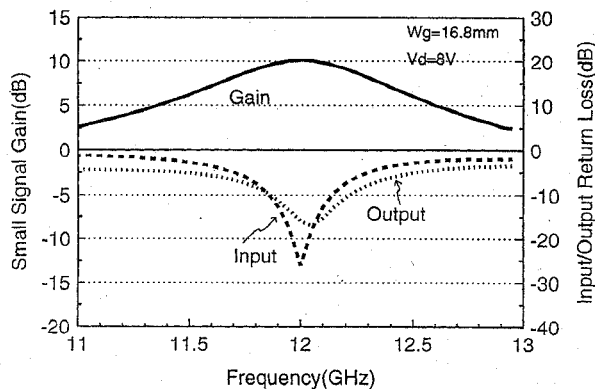


Fig. 1. Photograph of internally matched HJFET amplifier.

Fig. 2. Measured small signal response of power amplifier. $V_d = 8$ V.

III. AMPLIFIER PERFORMANCE

The power amplifier was mounted on a specially designed waveguide test fixture for evaluating gain, return loss and large-signal power characteristics. The fixture loss of 0.25 dB at 12 GHz was de-embedded from all measurement results.

Fig. 2 shows the measured small signal gain, input and output return losses of the power amplifier as a function of frequency. The small signal gain was 10.1 dB at 12 GHz with $V_d = 8$ V. The input and output return losses were less than -26 dB and -16 dB, respectively. The measured power characteristics are shown in Fig. 3. The fabricated power amplifier demonstrated an output power of 40.3 dBm (10.7 W) with 10.3 dB linear gain and 55% PAE with $V_d = 7$ V under C.W. operating conditions at 12 GHz. At $V_d = 8$ V, it delivered 40.9 dBm (12.3 W) output power with 10.1-dB linear gain and 48% PAE. To the authors' knowledge, this is the highest output power ever achieved from a single FET power amplifier at this frequency. At 1-dB gain-compression point, an

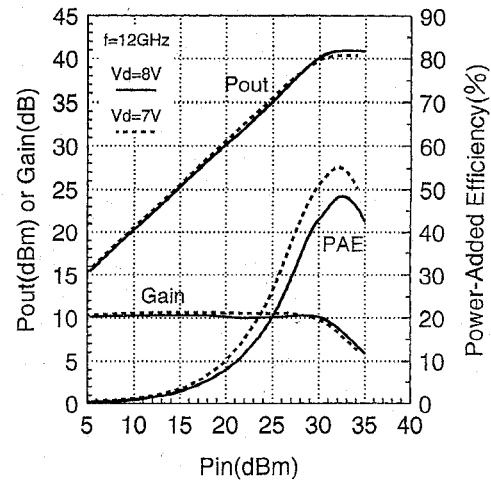
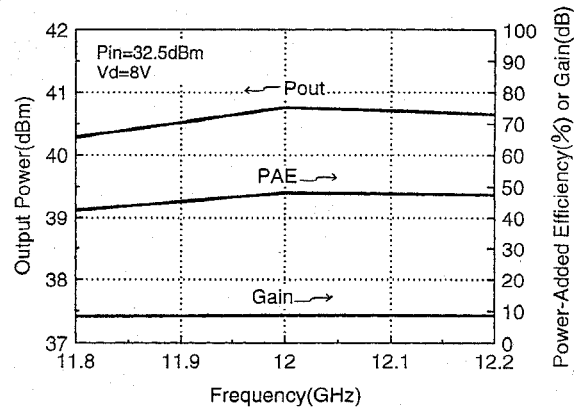
Fig. 3. Measured output power, gain, and power-added efficiency versus input power at 12 GHz for power amplifier. $V_d = 7$ and 8 V.

Fig. 4. Measured frequency response of power amplifier.

output power of 40.7 dBm (11.7 W) with an associated PAE of 47% was obtained with $V_d = 8$ V. These power performances can be attributed to higher drain current which was obtained by the optimized step-recessed structure, as well as to the use of low-impedance transmission line which significantly reduce the loss in the matching circuits at a designed frequency. The frequency dependence of the power characteristics were shown in Fig. 4. Over the 11.8–12.2 GHz frequency range, the amplifier exhibited 10.6–11.9 W output power with PAE of 42–48% and associated gain of 7.8–8.3 dB at $V_d = 8$ V with an input power of 32.5 dBm.

IV. CONCLUSION

High output power amplifier fabricated with a one-chip 0.45- μ m gate HJFET was demonstrated at Ku-band. The developed HJFET amplifier with 16.8-mm gate periphery delivered a 40.9-dBm (12.3 W) output power with 48% power-added efficiency and 10.1-dB linear gain at 12 GHz. To the authors' knowledge, this is the highest output power ever achieved from a single FET power amplifier at this frequency. Moreover, the developed HJFET exhibited more than 0.7-W/mm output power density, suggesting great potential of the HJFET approach for the future multi-10 W power amplifier

applications at Ku-band. The present power HJFET technology is promising for various satellite communication and radar system applications.

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REFERENCES

- [1] Y. Yamada, H. Kuroda, H. Izumi, T. Soezima, H. Wakamatsu, and S. Hori, "X and Ku band high power GaAs FET's," in *IEEE MTT-S Dig.*, 1988, pp. 847-850.
- [2] S. Tsuji, K. Semo, S. Sakamoto, T. Sakayori, T. Takagi, M. Yamanoushi, S. Takamiya, and Y. Kashimoto, "13 watts power GaAs FET for 14.0-14.5 GHz band," in *Proc. 3rd Int. Symp. Asia-Pacific Microwave Conf.*, 1990, pp. 537-539.
- [3] K. Hikosaka, Y. Hirachi, and M. Abe, "Microwave power double-heterojunction HEMT," *IEEE Education*, vol. ED-33, no. 5, pp. 583-589, 1986.
- [4] P. M. Smith, L. F. Lester, P. C. Chao, B. R. Lee, R. P. Smith, J. M. Ballingall, and K. H. G. Duh, "Millimeter-wave double heterojunction pseudomorphic power HEMTs," in *IEEE IEDM Dig.*, 1987, pp. 854-856.
- [5] J. C. Huang, G. Jackson, S. Shanfield, W. Hoke, P. Lyman, D. Atwood, P. Saledas, M. Schindler, Y. Tajima, A. Platzker, D. Masse, and H. Stats, "An AlGaAs/InGaAs pseudomorphic high electron mobility transistor for X- and Ku-band power applications," in *IEEE MTT-S Dig.*, 1991, pp. 713-716.
- [6] P. M. Smith, W. F. Kopp, P. Ho, P. C. Chao, R. P. Smith, K. Nordheden, and J. M. Ballingall, "Ku-band high efficiency high gain pseudomorphic HEMT," *Electron. Lett.* vol. 27, no. 3, 1991, pp. 270-271.
- [7] P. Saunier, W. S. Kopp, H. Q. Tserng, Y. C. Kao, and D. D. Heston, "A heterostructure FET with 75.8-percent power added efficiency at 10 GHz," in *IEEE MTT-S Dig.*, 1992, pp. 635-638.
- [8] H. Q. Tserng and P. Saunier, "A highly-efficient 7-watt 16 GHz monolithic pseudomorphic HEMT amplifier," in *IEEE MTT-S Dig.*, 1993, pp. 87-90.
- [9] S. Shanfield, A. Platzker, L. Aucoin, T. Kazior, B. I. Patel, A. Bertrand, W. Hoke, and P. Lyman, "One watt very high efficiency 10 and 18 GHz pseudomorphic HEMT's fabricated by dry first recess etching," in *IEEE MTT-S Dig.*, 1992, pp. 639-641.
- [10] M. Y. Kao, S. T. Fu, P. Ho, P. M. Smith, P. C. Chao, K. J. Nordheden, and S. Wang, "Very high voltage AlGaAs/InGaAs pseudomorphic power HEMTs," in *IEEE IEDM Dig.*, 1992, pp. 319-321.
- [11] S. T. Fu, L. F. Lester, and T. Rogers, "Ku-band high power high-efficiency pseudomorphic HEMT," in *IEEE MTT-S Dig.*, pp. 793-796, 1994.
- [12] K. Matsunaga, N. Iwata, and M. Kuzuhara, "High power pseudomorphic double-heterojunction field effect transistor with 26 V gate-drain breakdown voltages," in *Proc. 19th Int. Symp. GaAs and Related Compounds*, 1992, pp. 749-754.
- [13] K. Matsunaga, Y. Okamoto, and M. Kuzuhara, "Highly-efficient 6.6 W 12 GHz HJFET for power amplifier," in *IEEE IEDM Dig.*, pp. 895-898, 1994.